



Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

Seite:

PRINTED CIRCUIT BOARDS

01

4.11.2001

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 167 FR4 100 L71.100 P18_10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_167_FR4_100_L71.100_p18_10

Layers	in μ	Material	Build-Up	Assembly	
Layer-1	100 μ	Copper			
	100 μ	Prepreg			(100 μ PrePreg-Type: 2125)
	180 μ	Prepreg			(180 μ PrePreg-Type: 7628)
Layer-2	100 μ	Copper			
	710 μ	L-FR4			
Layer-3	100 μ	Copper			
	180 μ	Prepreg			
	100 μ	Prepreg			
Layer-99	100 μ	Copper			

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